

# Proven >

1,000,000,000  
SiP Packages

Used Indium Corporation  
materials in mobile FEM SiP  
devices in the last 2 years



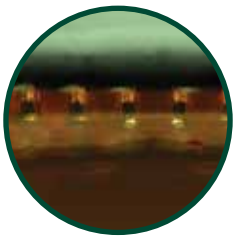
# Proven > 1,000,000,000 SiP Packages

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## Indium3.2HF Water-Soluble Solder Paste

- Fine-pitch printing without slumping or bridging
- Long stencil life
- Reflow without tombstoning
- Minimal voiding
- Ease of cleanability



## WS-580 Water-Soluble Flip-Chip Flux

- Consistent dipping performance
- Excellent solderability on various metallizations
- Minimal voiding
- High tackiness to prevent issues with die skewing



## 89HF-LV No-Clean PoP Flux

- Dipping or dispensing applications
- Air reflow
- Excellent solderability on various metallizations



## NC-26-S Ultra-Low Residue, No-Clean Flip-Chip Flux

- Suitable for TCB or mass reflow
- Minimal flux residue after reflow
  - Avoids flux contamination on die surface
  - Flux residue compatible with CUF/MUF (capillary underfill and molded underfill)

Contact our engineers today: [askus@indium.com](mailto:askus@indium.com)

Learn more: [www.indium.com/SiP](http://www.indium.com/SiP)

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